



## **Specification of Automotive MLCC**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21C332JAC1PNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 3.3 nF, 25V, ±5%, C0G, 0805

• AEC-Q 200 Specified

## A. Samsung Part Number

<u>CL</u> <u>21</u> <u>C</u> <u>332</u> <u>J</u> <u>A</u> <u>C</u> <u>1</u> <u>P</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor			
2	Size	0805 (inch code)	L:	$2.0 \pm 0.1 \text{ mm}$	W: $1.25 \pm 0.1 \text{ mm}$
3	Dielectric	C0G		8 Inner electrode	Ni
4	Capacitance	3.3 nF		Termination	Cu
⑤	Capacitance	±5 %		Plating	Sn 100% (Pb Free)
	tolerance			9 Product	Automotive
6	Rated Voltage	25 V		Grade code	Standard
7	Thickness	0.85 ± 0.1 mm		11 Packaging	Cardboard Type, 7" reel(4,000ea)

## B. Reliability Test and Judgement condition

	Performance	Test condition
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150℃
Exposure	Capacitance Change :	Measurement at 24±2hrs after test conclusion
	within ±2.5% or ±0.25pF whichever is larger	
	Q: 1000 min	
	IR : More than 10,000№ or 500№×μF	
	Whichever is Smaller	
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles
	Capacitance Change :	Measurement at 24±2hrs after test conclusion
	within ±2.5% or ±0.25pF whichever is larger	1 cycle condition :
	Q: 1000 min	-55+0/-3 °C (15±3min) -> Room Temp(1min.)
	IR : More than 10,000MΩ or 500MΩ×μF	-> 125+3/-0 ℃(15±3min) -> Room Temp(1min.)
	Whichever is Smaller	
Destructive Physical	No Defects or abnormalities	Per EIA 469
Analysis		
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle
	Capacitance Change :	Heat (25~65 °C) and humidity (80~98%), Unpowered
	within ±2.5% or ±0.25pF whichever is larger	measurement at 24±2hrs after test conclusion
	Q: 350 min	
	IR : More than 10,000MΩ or 500MΩ×μF	
	Whichever is Smaller	
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85°C/85%RH, Rated Voltate and 1.3~1.5V,
	Capacitance Change :	Add 100kohm resistor
	within ±2.5% or ±0.25pF whichever is larger	Measurement at 24±2hrs after test conclusion
	Q: 200 min	The charge/discharge current is less than 50mA.
	IR : More than 500MΩ or 25MΩ×μF	
	Whichever is Smaller	
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125 ℃, 200% Rated Voltage,
Operating Life	Capacitance Change :	Measurement at 24±2hrs after test conclusion
	within ±3.0% or ±0.3pF whichever is larger	The charge/discharge current is less than 50mA.
	Q: 350 min	
	IR : More than 10,000№ or 500№×μF	
	Whichever is Smaller	

	Performance	Test condition			
External Visual	No abnormal exterior appearance	Visual inspection			
Physical Dimensions	Within the specified dimensions	Using The calipers			
Mechanical Shock	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec.	Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks)  Peakvalue Duration Wave Velocity  1,500G 0.5ms Half sine 4.7m/sec.			
Vibration	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec.	5g's for 20min., 12cycles each of 3 orientations, Use 8"x5" PCB 0.031" Thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10~2000Hz.			
Resistance to	Appearance : No abnormal exterior appearance	Solder pot : 260±5 ℃, 10±1sec.			
Solder Heat	Capacitance Change : within ±2.5% or ±0.25pF whichever is larger Q, IR : initial spec.				
Thermal Shock	Appearance : No abnormal exterior appearance Capacitance Change : within ±2.5% or ±0.25pF whichever is larger Q, IR : initial spec.	-55 ℃/+125 ℃. Note: Number of cycles required-300, Maximum transfer time-20 sec, Dwell time-15min. Air-Air			
ESD	Appearance : No abnormal exterior appearance Capacitance Change : within ±2.5% or ±0.25pF whichever is larger Q, IR : initial spec.	AEC-Q200-002			
Solderability	95% of the terminations is to be soldered evenly and continuously	<ul> <li>a) Preheat at 155 ℃ for 4 hours, Immerse in solder for 5s at 245±5 ℃</li> <li>b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 ℃</li> <li>c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 ℃</li> <li>solder: a solution ethanol and rosin</li> </ul>			
Electrical	Capacitance : Within specified tolerance	The Capacitance /Q should be measured at 25℃,			
Characterization	Q: 1000 max.  IR(25℃): More than 100,000MΩ or 1,000MΩ×μF  IR(125℃): More than10,000MΩ or 100MΩ×μF  Whichever is Smaller  Dielectric Strength	1版±10%, 1.0±0.2Vrms I.R. should be measured with a DC voltage not exceeding Rated Voltage @25℃, @125℃ for 60~120 sec. Dielectric Strength: 250% of the rated voltage for 1~5 seconds			
Board Flex	Appearance: No abnormal exterior appearance Capacitance Change: within ±5.0% or ±0.5pF whichever is larger	Bending to the limit (3mm) for 5 seconds			
Terminal	Appearance : No abnormal exterior appearance	18N, for 60±1 sec.			
Strength(SMD)	Capacitance Change : within ±2.5% or ±0.25pF whichever is larger				
Beam Load	Destruction value should not be exceed Chip Length < 2.5mm a) Chip Thickness > 0.5mm : 20N b) Chip Thickness ≤ 0.5mm : 8N	Beam speed 0.5±0.05mm/sec			
Temperature	COG				
characteristics	(From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)				

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}\!\!\mathrm{C}$  , 10sec. Max )

Meet IPC/JEDEC J-STD-020 D Standard

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.